

Hariklia Deligianni

List of Publications by Year in descending order

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Version: 2024-02-01

19
papers

1,041
citations

687363

13
h-index

940533

16
g-index

19
all docs

19
docs citations

19
times ranked

1350
citing authors

#	ARTICLE	IF	CITATIONS
1	Embrace the Journey and Harness the Power of Your Network: A Woman's Perspective. ECS Meeting Abstracts, 2019, , .	0.0	0
2	Scalable Nanostructured Carbon Electrode Arrays for Enhanced Dopamine Detection. ACS Sensors, 2018, 3, 799-805.	7.8	56
3	Control of Growth Front Evolution by Bi Additives during ZnAu Electrodeposition. Nano Letters, 2018, 18, 1093-1098.	9.1	30
4	Preface"JES Focus Issue on the Brain and Electrochemistry Honoring R. Mark Wightman and Christian Amatore. Journal of the Electrochemical Society, 2018, 165, Y13-Y13.	2.9	0
5	GaN Devices on a 200 mm Si Platform Targeting Heterogeneous Integration. IEEE Electron Device Letters, 2017, 38, 1094-1096.	3.9	21
6	Surface PEDOT:Nafion Coatings for Enhanced Dopamine, Serotonin and Adenosine Sensing. Journal of the Electrochemical Society, 2017, 164, G129-G138.	2.9	37
7	The Brain and Electrochemistry. Electrochemical Society Interface, 2017, 26, 47-47.	0.4	0
8	Simplified formation process for Cu ₂ ZnSnS ₄ -based solar cells. Thin Solid Films, 2014, 573, 148-158.	1.8	15
9	Electrodeposited Cu ₂ ZnSnSe ₄ thin film solar cell with 7% power conversion efficiency. Progress in Photovoltaics: Research and Applications, 2014, 22, 58-68.	8.1	142
10	A Diffusion Barrier for Flexible Thin Film Photovoltaics. Journal of the Electrochemical Society, 2013, 160, D102-D106.	2.9	4
11	A High Efficiency Electrodeposited Cu ₂ ZnSnS ₄ Solar Cell. Advanced Energy Materials, 2012, 2, 253-259.	19.5	504
12	Electrodeposition Fueled by Newman and Tobias. Electrochemical Society Interface, 2010, 19, 39-42.	0.4	1
13	Effect of Additives on Shape Evolution during Electrodeposition. Journal of the Electrochemical Society, 2008, 155, D223.	2.9	22
14	Effect of Additives on Shape Evolution during Electrodeposition. Journal of the Electrochemical Society, 2007, 154, D584.	2.9	43
15	Numerical Simulation of Electrochemical Planarization of Copper Overburden. Journal of the Electrochemical Society, 2005, 152, C652.	2.9	8
16	Effect of Benzotriazole on the Anisotropic Electrolytic Etching of Copper. Journal of the Electrochemical Society, 1998, 145, 3016-3024.	2.9	19
17	Alloying of a Less Noble Metal in Electrodeposited Cu Through Underpotential Deposition. Journal of the Electrochemical Society, 1995, 142, 2244-2249.	2.9	32
18	Effect of Fluid Flow on Convective Transport in Small Cavities. Journal of the Electrochemical Society, 1990, 137, 818-824.	2.9	64

#	ARTICLE	IF	CITATIONS
19	The Role of Mass Transport on Anisotropic Electrochemical Pattern Etching. Journal of the Electrochemical Society, 1988, 135, 1093-1100.	2.9	43